

NEW

MODEL 6410

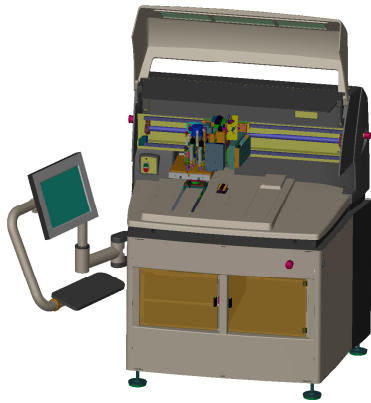
AUTOMATIC HIGH ACCURACY DISPENSING SYSTEM

Performs **Dispensing** and **Stamping** of different adhesives, flux and other materials.

Versatile and **User Friendly** machine based on a PC platform running under Windows XP®.

Fully automatic system designed for highest flexibility and easy operation.

Very High Accuracy closed loop servo systems control the X, Y motion of the head.



High resolution **Digital Vision** and **Image Processing** system.

Dual Magnification down looking camera moving on the **Focus** axis with 20 mm travel and **Auto Focus**.

Very Large Work Area allows handling of large PC boards.

Cold and **Heated** work holders handling a wide variety of substrates.

Adhesive is applied in single dot, multi dot and X-Y shape patterns by the **Time-Pressure** or **Positive Displacement Pumps**.

The machine can handle a variety of pumps including **Auger** screw based or other systems.

Underfill dispensing process for flip chip applications.

Stamping (Pin Transfer) less than **75 µm** diameter adhesive dots.

Library of complex pre-taught dispense shapes.



Specification Highlights

Work Area: up to 20" x 12".
Substrates: Lead Frames, Ceramic, Silicon
Wafers, FR4, Metal, etc.

Dot size range from: 0.075 mm (by stamping).
Placement Accuracy: 10 µm @ 3 sigma.
Throughput: up to 3600 dots/hour.
